

## DZ2J082×0L

### Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

#### ■ Features

- Excellent rising characteristics of zener current  $I_Z$
- Low zener operating resistance  $R_Z$
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

#### ■ Marking Symbol: JJ or JU

#### ■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

#### ■ Absolute Maximum Ratings $T_a = 25\text{ }^{\circ}\text{C}$

| Parameter                             | Symbol | Rating      | Unit |
|---------------------------------------|--------|-------------|------|
| Repetitive peak forward current       | IFRM   | 200         | mA   |
| Total power dissipation <sup>*1</sup> | PT     | 200         | mW   |
| Electrostatic discharge <sup>*2</sup> | ESD    | ±8          | kV   |
| Junction temperature                  | Tj     | 150         | °C   |
| Operating ambient temperature         | Topr   | -40 to +85  | °C   |
| Storage temperature                   | Tstg   | -55 to +150 | °C   |

Note) \*1 Mounted on glass epoxy print board ( 45 mm × 45 mm × 1 mm )

Solder in ( Recommended land pattern )

\*2 Test method : IEC61000\_4\_2

( C = 150 pF, R = 330 Ω, Contact discharge : 10 times )

#### ■ Electrical Characteristics $T_a = 25\text{ }^{\circ}\text{C} \pm 3\text{ }^{\circ}\text{C}$

| Parameter  | Symbol | Conditions  | Min  | Typ | Max  | Unit  |
|--|--------|-------------|------|-----|------|-------|
| Forward voltage  | VF     | IF = 10 mA  |      |     | 1.0  | V     |
| Zener voltage <sup>*1, *2</sup>                        | VZ     | IZ = 5 mA   | 7.79 |     | 8.61 | V     |
| Zener operating resistance                             | RZ     | IZ = 5 mA   |      |     | 20   | Ω     |
| Zener rise operating resistance                        | RZK    | IZ = 0.5 mA |      |     | 60   | Ω     |
| Reverse current  | IR     | VR = 5 V    |      |     | 0.1  | μA    |
| Temperature coefficient of zener voltage <sup>*3</sup> | SZ     | IZ = 5 mA   |      | 4.7 |      | mV/°C |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

3. \*1 The temperature must be controlled 25 °C for VZ measurement.

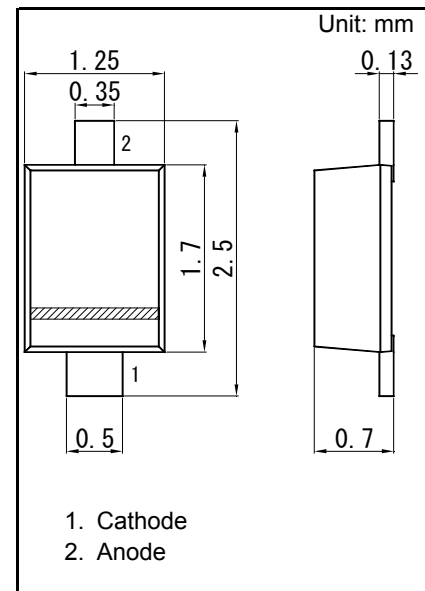
VZ value measured at other temperature must be adjusted to VZ (25 °C).

\*2 VZ guaranteed 20 ms after current flow

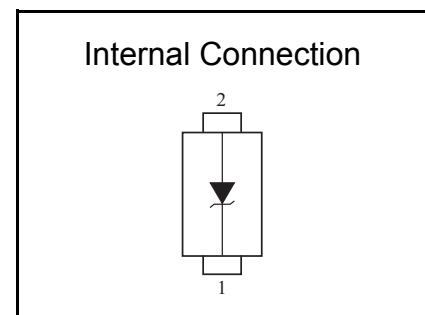
\*3 Tj = 25 °C to 150 °C

#### Rank classification

|                |              |              |
|----------------|--------------|--------------|
| Code           | M            | 0            |
| Rank           | M            | No-rank      |
| VZ             | 8.03 to 8.43 | 7.79 to 8.61 |
| Marking symbol | JU           | JJ           |

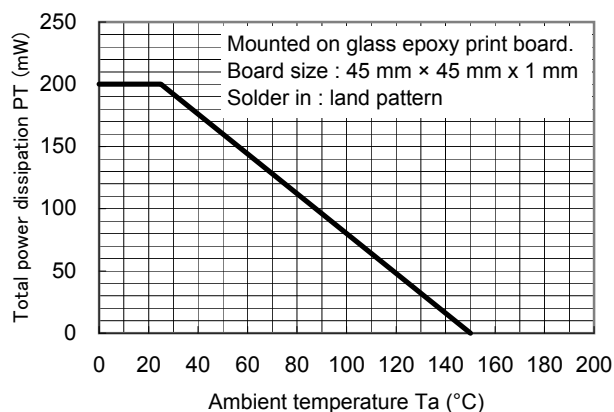


|           |             |
|-----------|-------------|
| Panasonic | SMini2-F5-B |
| JEITA     | SC-90A      |
| Code      | —           |

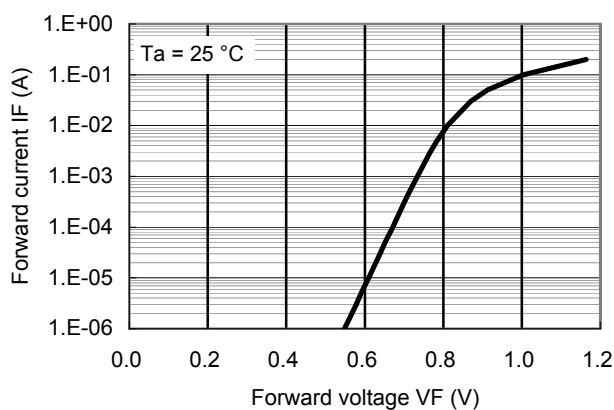


Technical Data ( reference )

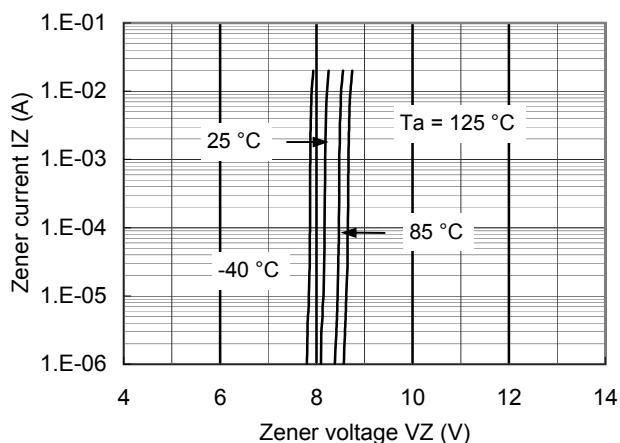
PT - Ta



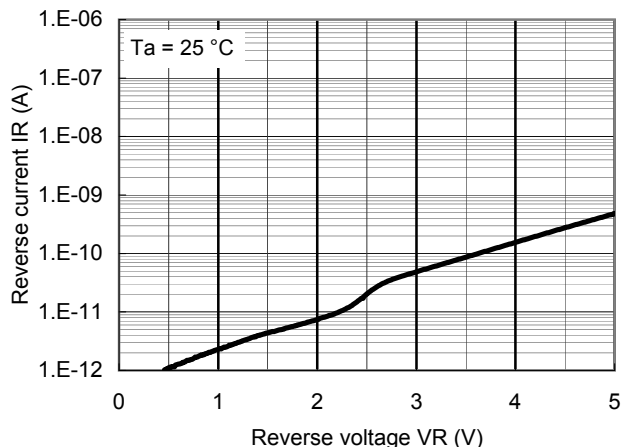
IF - VF



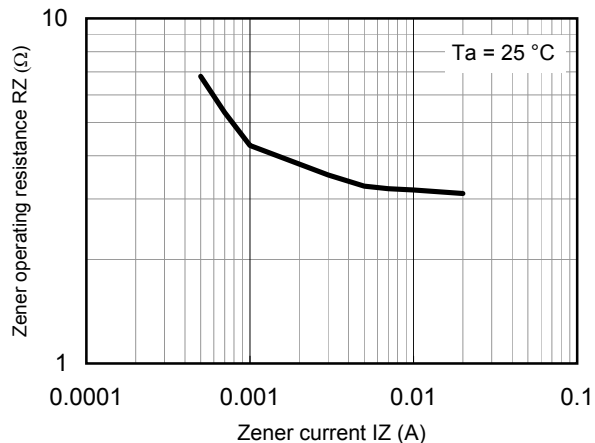
IZ - VZ



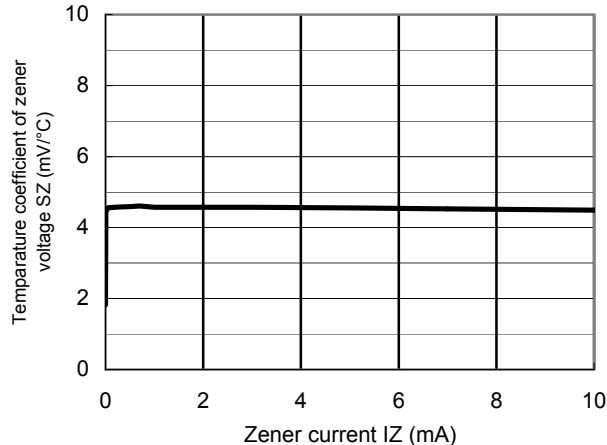
IR - VR



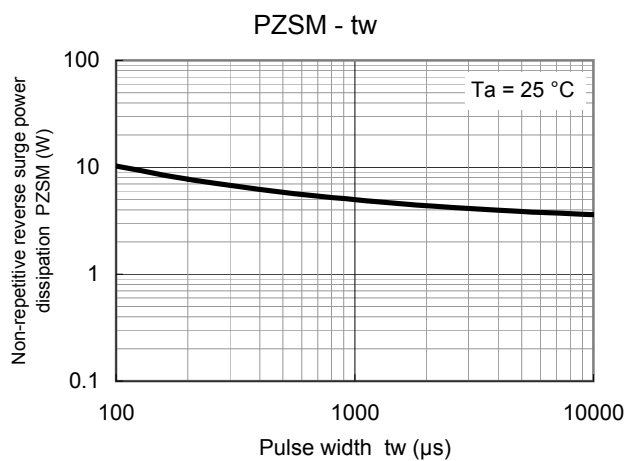
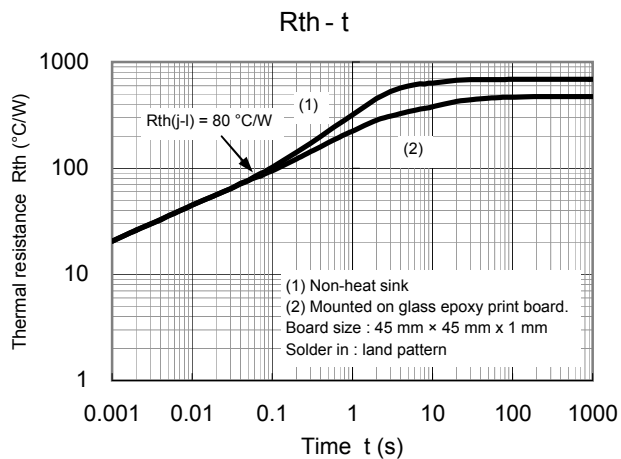
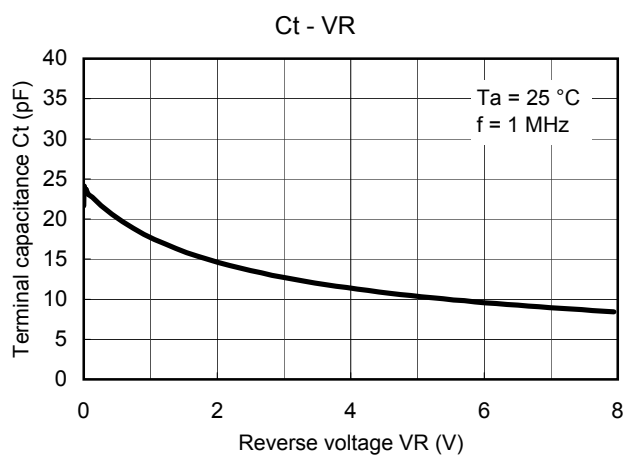
RZ - IZ



SZ - IZ

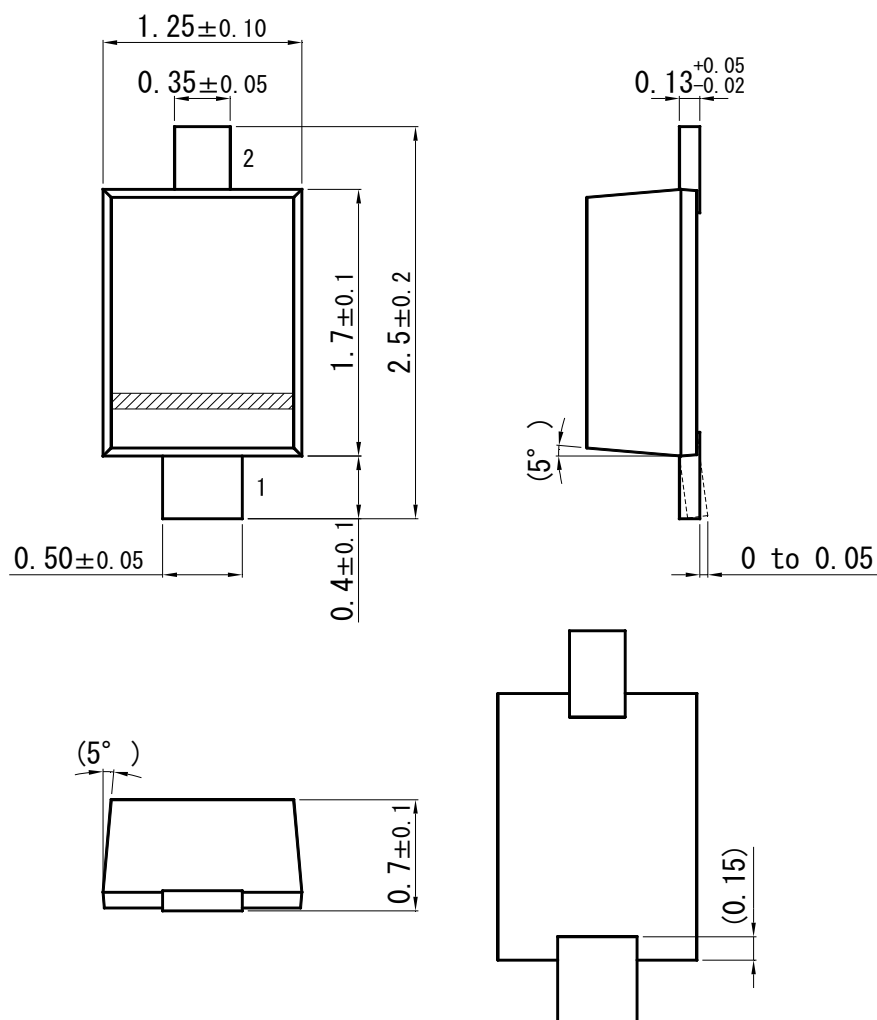


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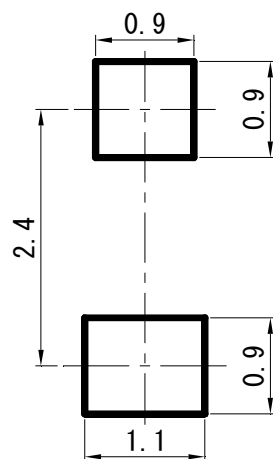


SMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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